

3.0A SCHOTTKY BARRIER RECTIFIER

Product Summary

B350BE/B350CE B360BE/B360CE

| V _{RRM} (V) | I _O (A) | V _F Max (V) @ +25°C | I _R Max (mA) @ +25°C |
|----------------------|--------------------|-----------------------------------|------------------------------------|
| 50 | 3 | 0.65 | 0.1 |
| 60 | 3 | 0.65 | 0.2 |

Description and Applications

The Schottky rectifier providing low V_F and excellent reverse leakage stability at high temperatures, this device is ideal for use in general rectification applications such as:

- Boost Diode
- Blocking Diode
- · Recirculating Diode

Features and Benefits

- Reduced Low Forward Voltage Drop (V_F); Better Efficiency and Cooler Operation
- Reduced High-Temperature Reverse Leakage; Increased Reliability against Thermal Runaway Failure in High Temperature Operation
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SMB, SMC
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ³
- Polarity: Cathode Band
- Weight: SMB- 0.093 grams (Approximate)
 SMC- 0.21 grams (Approximate)

SMB/SMC







Bottom View

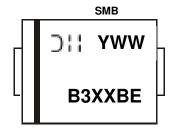
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|-------------|------|-------------------|
| B3XXBE-13 | SMB | 3,000/Tape & Reel |
| B3XXCE-13 | SMC | 3.000/Tape & Reel |

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

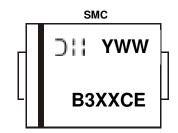


B3XXBE = Product Type Marking Code, ex: B350BE

| Sill = Manufacturers' Code Marking
| YWW = Date Code Marking
| Y = Last Digit of Year (ex: 7 for 2017)
| WW = Week Code (01 to 53)



Marking Information (Cont.)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

| Characteristic | Symbol | B350BE/B350CE | B360BE/B360CE | Unit |
|---|--|---------------|---------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | $egin{array}{c} egin{array}{c} egin{array}$ | 50 | 60 | > |
| Average Rectified Output Current | lo | 3 | 3 | Α |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load | I _{FSM} | 8 | 0 | А |

Thermal Characteristics

| Characteristic | | Symbol | Value | Unit |
|---|-----|-----------------------------------|-------------|--------|
| Typical Thermal Resistance Junction to Ambient (Note 5) | SMB | Б | 90 | °C/W |
| | SMC | $R_{\theta JA}$ | 70 | - C/VV |
| Typical Thermal Resistance Junction to Case (Note 5) | SMB | В | 50 | °C/W |
| | SMC | $R_{\theta JC}$ | 30 | C/VV |
| Operating and Storage Temperature Range | | T _J , T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Min | Тур | Max | Unit | Test Condition |
|--------------------------|----------------------------------|----------------|-----|-------------------|-----------------|------|--|
| Forward Voltage Drop | | V _F | | 0.55 0.52 | 0.65 — | I V | $I_F = 3A, T_J = +25$ °C $I_F = 3A, T_J = +125$ °C |
| Leakage Current (Note 6) | B350BE/ B350CE B360BE/ B360CE | I _R | | _ _ _ 25 | 0.1 0.2 — | mA | $V_R = 50V, T_J = +25^{\circ}C$ $V_R = 60V, T_J = +25^{\circ}C$ $V_R = 60V, T_J = +125^{\circ}C$ |
| Typical Capacitance | | Ст | | 110 | _ | pF | $V_R = 4.0V$, $f = 1MHz$ |

Notes: 5. Device mounted on FR-4 substrate, 0.4"*0.5", 2oz, single-sided, PC boards with 0.2"*0.25" copper pad.

6. Short duration pulse test used to minimize self-heating effect.



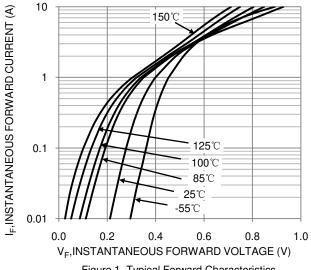


Figure 1. Typical Forward Characteristics

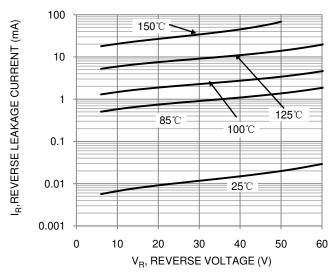
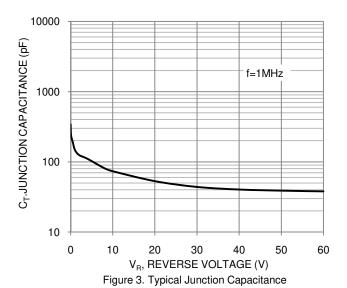


Figure 2. Typical Reverse Characteristics



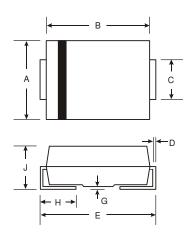
3.5 3 I_F, DC FORWARD CURRENT (A) 2.5 2 Note 5 1.5 1 0.5 0 25 125 75 100 150 T_A , AMBIENT TEMPERATURE (°C) Figure 4. DC Forward Current Derating



Package Outline Dimensions

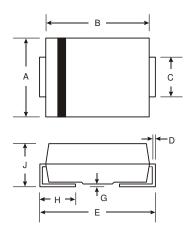
Please see http://www.diodes.com/package-outlines.html for the latest version.

SMB



| | SMB | | | |
|----------------------|------|------|--|--|
| Dim | Min | Max | | |
| Α | 3.30 | 3.94 | | |
| В | 4.06 | 4.57 | | |
| C | 1.96 | 2.21 | | |
| D | 0.15 | 0.31 | | |
| Е | 5.00 | 5.59 | | |
| G | 0.05 | 0.20 | | |
| Н | 0.76 | 1.52 | | |
| 7 | 2.00 | 2.50 | | |
| All Dimensions in mm | | | | |

SMC



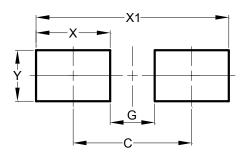
| SMC | | | | |
|----------------------|------|------|--|--|
| Dim | Min | Max | | |
| Α | 5.59 | 6.22 | | |
| В | 6.60 | 7.11 | | |
| С | 2.75 | 3.18 | | |
| D | 0.15 | 0.31 | | |
| Е | 7.75 | 8.13 | | |
| G | 0.10 | 0.20 | | |
| Н | 0.76 | 1.52 | | |
| J | 2.00 | 2.50 | | |
| All Dimensions in mm | | | | |



Suggested Pad Layout

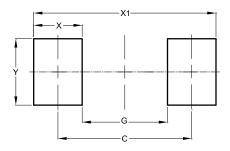
Please see http://www.diodes.com/package-outlines.html for the latest version.

SMB



| Dimensions | Value (in mm) |
|------------|---------------|
| С | 4.30 |
| G | 1.80 |
| Х | 2.50 |
| X1 | 6.80 |
| Υ | 2.30 |

SMC



| Dimensions | Value (in mm) |
|------------|------------------|
| С | 6.90 |
| G | 4.40 |
| X | 2.50 |
| X1 | 9.40 |
| Υ | 3.30 |



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